

8030 SERIES

FULLY AUTOMATIC 12" TWIN DICING SYSTEM



CONFIGURATION:

- ▶ Blade O.D.: 2"-3"
- ▶ Size: Ø12", 12" X 12"

FEATURE & BENEFITS:

- Bridge type frame
- Flexibility - Supports Hub and Hubless blades up to 3" O.D.
- Dual microscopes, fixed non-contact sensors and two dress stations
- Spindles of 1.8 kW or 2.2 kW high power (for challenging applications)
- Superior vision system with continuous zoom magnification
- Intuitive operation interface using a large 19" touch screen monitor

EASE OF USE:

- The 8030 operates with the ADT intuitive New graphic User Interface (NUI) and includes two touch - screens: 19" monitor for the main screen and 17" monitor maintenance screen.

OTHER KEY FEATURES OF IMPORTANCE:

- Highest dicing process speeds - Lowest cost
- Support up to 12" x 12" square products
- Industrial PC based on Win 10 OS
- Air bearing feed axis (X)
- Fast & Simple blade change with a spindle shaft lock mechanism
- Fast automatic alignment and cut positioning for increased throughput
- Automatic Kerf inspection and quality analysis for maximum precision
- Process data logging and statistical analysis
- SECS / GEM platform ready
- Load port ready for factory automation
- All electronic on top of the cut chamber

LEADING APPLICATIONS

- Silicon wafers for Memory and Logic products
- MEMS (micro-electromechanical system)
- CMOS Image Sensors (CIS)
- Packaging (FOPLP, FOWLP, QFN, BGA)

SPECIFICATIONS:

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Workpiece Size	Ø 8", Ø 12" or 12" x 12" Square
Spindle	Two facing 1.8kW Shaft Lock spindles (Optional 2.2kW) Max. 60,000 rpm
Blade Size	2" - 3"
Y1 / Y2 Axis:	
Drive	Ball bearing lead screw
Control	Linear encoder for each Y axis
Resolution	0.1 µm
Cumulative Accuracy	1.5 µm
Indexing Accuracy	1.0 µm
Cutting range	350 mm
X Axis:	
Drive	Air Slide
Feed Rate	Ball bearing lead screw
Cutting range	Up to 600 mm/sec (Optional for 1000 mm/sec) 310 mm
Z1 / Z2 Axis:	
Resolution	0.2 µm
Repeatability	1.0 µm
Max. stroke	50 mm (for 2.188" blade OD)
Ø Axis:	
Drive	Closed-loop, Direct-drive
Repeatability	4 arc-sec
Stroke	380°
Vision System	USB3 camera, High bright LED illumination (vertical & oblique)
Cleaning Station	Full rinse and dry cycle
Spinning speed	100-3,000 rpm
Cleaning Method	Atomized cleaning capabilities
Wafer Handling system	Slot to slot integrity Inspection drawer
Standard Features	Automatic: Alignment, Kerf check, Y offset and cut verify
User Interface	2 touch screens: 19" monitor as main screen and 17" monitor for maintenance NUI (New Graphic User Interface) and multi language support
Options	UV Station, CO ₂ Bubbler, ESD Air Blower Kit, Multiple angle capability Dicing Floor Management (SECS GEM)
Utilities	
Electrical	200-240 VAC, 50/60 Hz, single phase
Air	500 L/min @ 5.5 bar
Spindle Coolant (per spindle)	1.1 L/min
Cutting water (per spindle)	Up to 3 L/min
Dimensions	
WxDxH	1145mm x 1687mm x 1830mm
Weight	1500 kg
Environmental	Room Temperature: 20°C to 25°C ± 1°C (77°F ± 1.8°F) Humidity: Less than 70% relative humidity (non-condensing) Cutting water / Spindle water Temperature: ± 1°C (± 1.8°F) from room temperature Floor must be vibration free

Note: Specifications are subject to change without notice.